

L Number	Hits	Search Text	DB	Time stamp
2	1207	(CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) and abrasive and pad and (solidif\$4 or dispers\$3)	USPAT; EPO; JPO; IBM_TDB	2003/02/19 14:51
3	1416	(CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) and abrasive and pad and slurry and (alumina or silica or ceria) and (aluminum or al or titanium or ti or copper or Cu)	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:21
4	4113	pad with abrasive	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:22
5	920	((CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) and abrasive and pad and slurry and (alumina or silica or ceria) and (aluminum or al or titanium or ti or copper or Cu)) and (pad with abrasive)	USPAT; EPO; JPO; IBM_TDB	2003/02/19 14:56
6	76	((CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) and abrasive and pad and slurry and (alumina or silica or ceria) and (aluminum or al or titanium or ti or copper or Cu)) and (pad with abrasive)) and organic and oxidizer	USPAT; EPO; JPO; IBM_TDB	2003/02/19 14:57
7	80	(CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) and abrasive and pad and slurry and (alumina or silica or ceria) and (aluminum or al or titanium or ti or copper or Cu) and (benzotriazole or BTA)	USPAT; EPO; JPO; IBM_TDB	2003/02/19 15:52
8	771	(CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) same abrasive and pad and slurry and (alumina or silica or ceria) same (aluminum or al or titanium or ti or copper or Cu)	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:18
9	516	((CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) same abrasive and pad and slurry and (alumina or silica or ceria) same (aluminum or al or titanium or ti or copper or Cu)) and semiconductor	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:17
10	110	(CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) same abrasive same pad same slurry same (alumina or silica or ceria) same (aluminum or al or titanium or ti or copper or Cu)	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:20
11	1733	((438/690) or (438/691) or (438/692) or (438/693)).CCLS.	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:20
12	407	((438/690) or (438/691) or (438/692) or (438/693)).CCLS.) and ((CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) and abrasive and pad and slurry and (alumina or silica or ceria) and (aluminum or al or titanium or ti or copper or Cu))	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:21
13	1071	pad same attach\$ same abrasive	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:22

14	44	(((438/690) or (438/691) or (438/692) or (438/693)).CCLS.) and ((CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) and abrasive and pad and slurry and (alumina or silica or ceria) and (aluminum or al or titanium or ti or copper or Cu))) and (pad same attach\$ same abrasive)	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:22
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